

ABSTRACT

EPOXY RESIN COMPOSITION AND ELECTRONIC COMPONENT DEVICE

An epoxy resin composition includes an epoxy resin containing a compound represented by the following Formula (1); and a curing agent containing at least one selected from the group consisting of biphenylene-type phenol aralkyl resins, phenol aralkyl resins, and triphenylmethane-type phenol resins. Each R_1 independently represents a hydrogen atom or a monovalent hydrocarbon group having from 1 to 6 carbon atoms; each R_2 represents a substituent represented by Formula (a); m represents a number from 0 to 20; p represents from 0.5 to 2.0; and each of R_3 s independently represents a hydrogen atom or a monovalent hydrocarbon group having from 1 to 6 carbon atoms

